

Description

The CMP100160U is the P-Channel enhancement mode power field effect transistors with high cell density, trench technology. This high density process and design have been optimized switching performance and especially tailored to minimize on-state resistance.

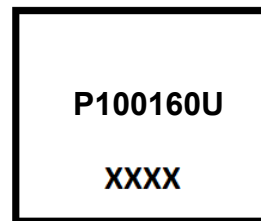
Features

- V_{DS} : -100V
- I_D : -10A
- $R_{DS(on)}$ (@ $V_{GS}=-10V$): < 215m Ω
- $R_{DS(on)}$ (@ $V_{GS}=-4.5V$): < 245m Ω
- High density cell design for extremely low $R_{DS(on)}$
- Excellent on-resistance and DC current capability

Applications

- Cellular Handsets and Accessories
- Personal Digital Assistants
- Portable Instrumentation
- Load switch

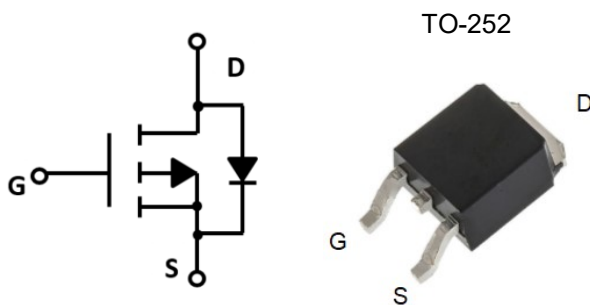
Marking Information



Marking Code = P100160U

Date Code = XXXX

Equivalent Circuit and Pin Configuration



Ordering Information

Part Number	Packaging	Remark
CMP100160U	2500/Tape & Reel	ROHS

Absolute Maximum Ratings (Tc=25 °C unless otherwise noted)

Parameter	Symbol	Maximum	Unit	
Drain-source Voltage	V_{DS}	-100	V	
Gate-source Voltage	V_{GS}	± 20	V	
Continuous Drain Current ⁽¹⁾	I_D	$T_C=25^\circ C$	-10	A
		$T_C=100^\circ C$	-6.4	A
Pulsed Drain Current ⁽²⁾	I_{DM}	-40	A	
Total Power Dissipation ⁽³⁾	$P_D @ T_C=25^\circ C$	42	W	
	Derating Factor above 25°C	0.33	W/°C	
Thermal Resistance Junction-to-Case ⁽³⁾	$R_{\theta JC}$	3	°C/W	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C	

Electrical Characteristics (TC=25 °C unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BVDSS	VGS=0V, ID=-250μA	-100			V
Zero Gate Voltage Drain Current	IDSS	VDS=-100V, VGS=0V, TC=25°C			-5	μA
Gate-Body Leakage Current	IGSS	VGS=±20V, VDS=0V			±100	nA
Gate Threshold Voltage	VGS(th)	VDS=VGS, ID=-250μA	-1.0		-3.0	V
Static Drain-Source on-Resistance	RDS(on)	VGS=-10V, ID=-6A		180	215	mΩ
		VGS=-4.5V, ID=-3A		190	245	
Diode Forward Voltage	VSD	IS=-10A, VGS=0V		-0.8	-1.2	V
Maximum Body-Diode Continuous Current	IS				-10	A
Dynamic Parameters						
Input Capacitance	Ciss	VDS=-25V, VGS=0V, f=1MHz		1320		pF
Output Capacitance	Coss			42		
Reverse Transfer Capacitance	Crss			30		
Switching Parameters						
Total Gate Charge	Qg	VGS=-10V, VDS=-50V, ID=-8A		19		nC
Gate Source Charge	Qgs			0.8		
Gate Drain Charge	Qgd			1.2		
Turn-on Delay Time	tD(on)	VGS=-10V, VDD=-50V, ID=-8A, RGEN=2.2Ω		6.6		ns
Turn-on Rise Time	tr			4.1		
Turn-off Delay Time	tD(off)			90		
Turn-off Fall Time	tf			21.6		

Noted: (1) Pulse Test: Pulse Width ≤ 300us, Duty cycle ≤ 2%.

(2) The test with different tester may be preformed differently.

(3) Device mounted on FR-4 PCB , 1 inch x 0.85 inch x 0.062 inch with 2oz. Copper , t ≤ 10s.

Typical Performance Characteristics

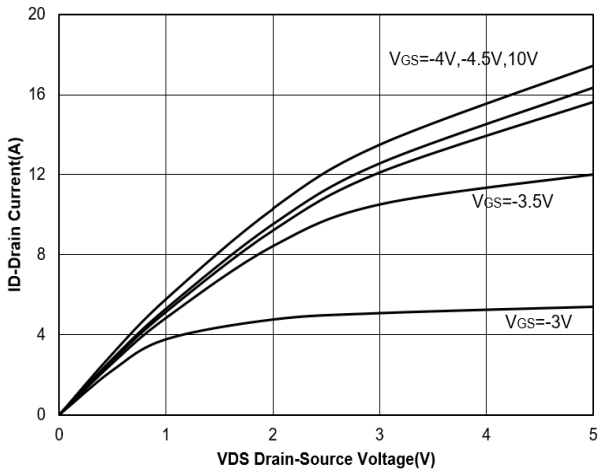


Figure 1. Output Characteristics

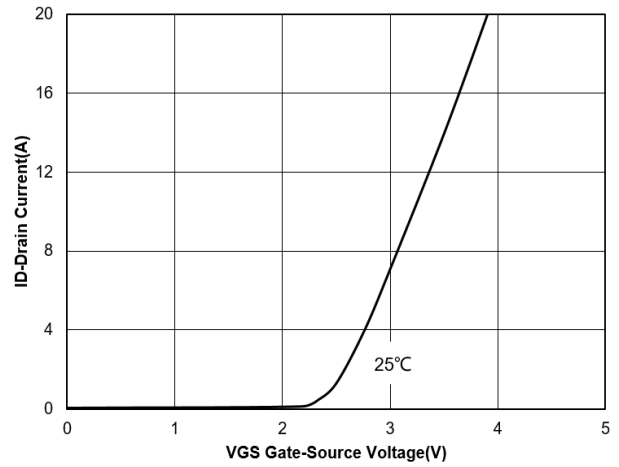


Figure 2. Transfer Characteristics

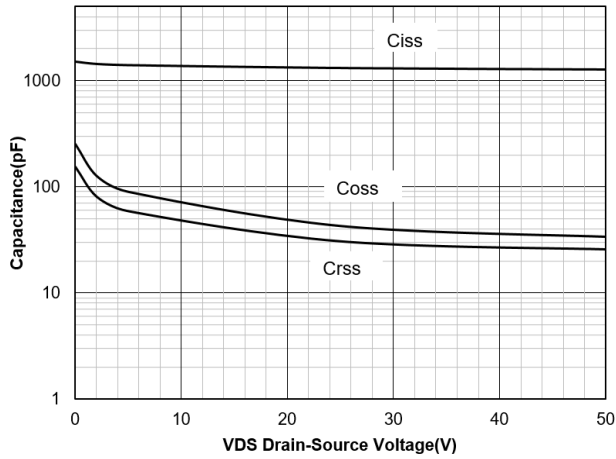


Figure 3. Capacitance Characteristics

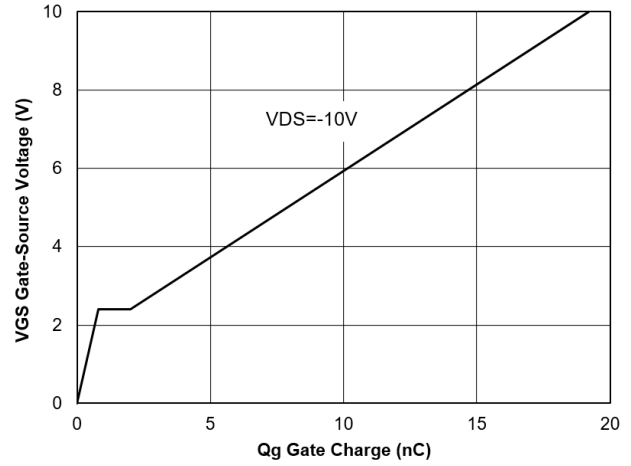


Figure 4. Gate Charge

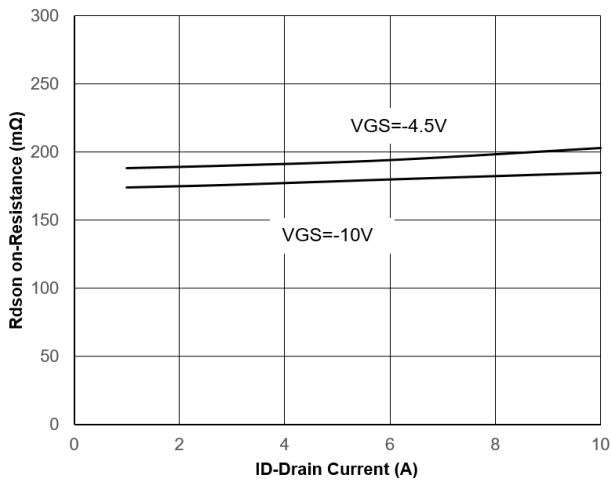


Figure 5. Drain-Source on Resistance

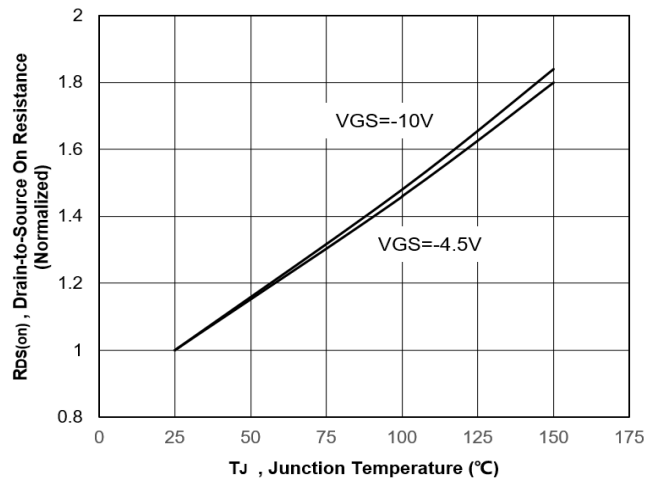


Figure 6. Normalized On-Resistance

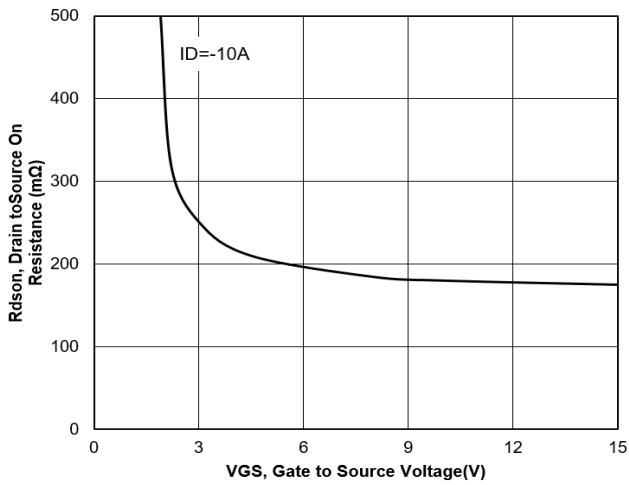


Figure 7. Typical Drain to Source ON Resistance VS Gate Voltage and Drain Current

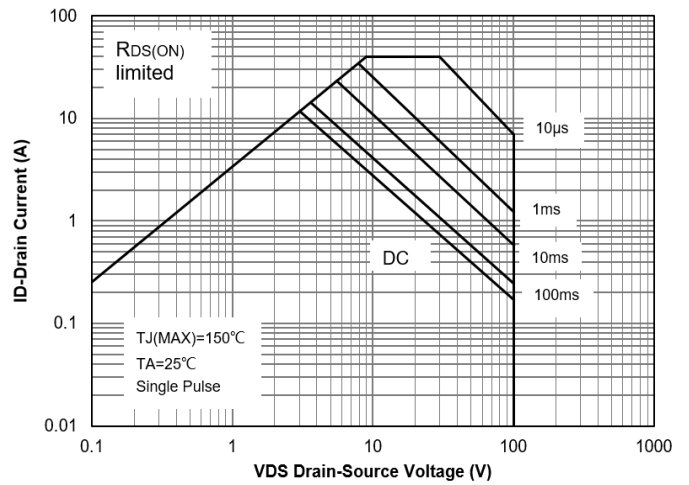


Figure 8. Safe Operation Area

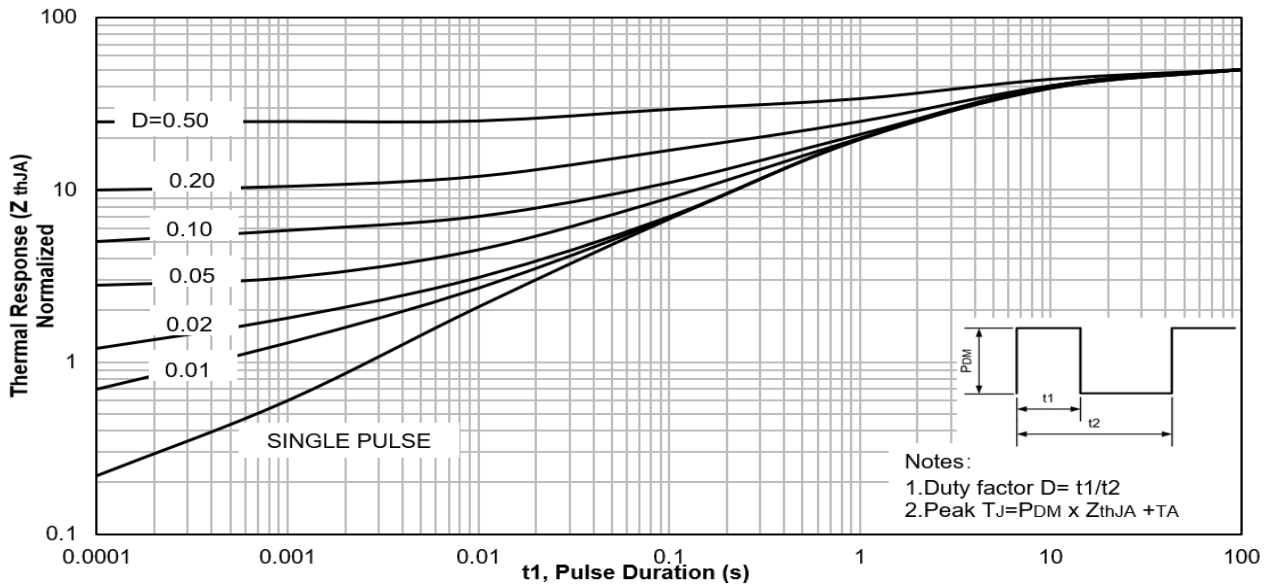


Figure 9. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

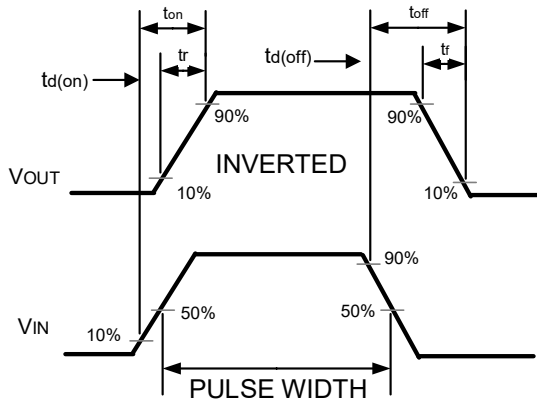
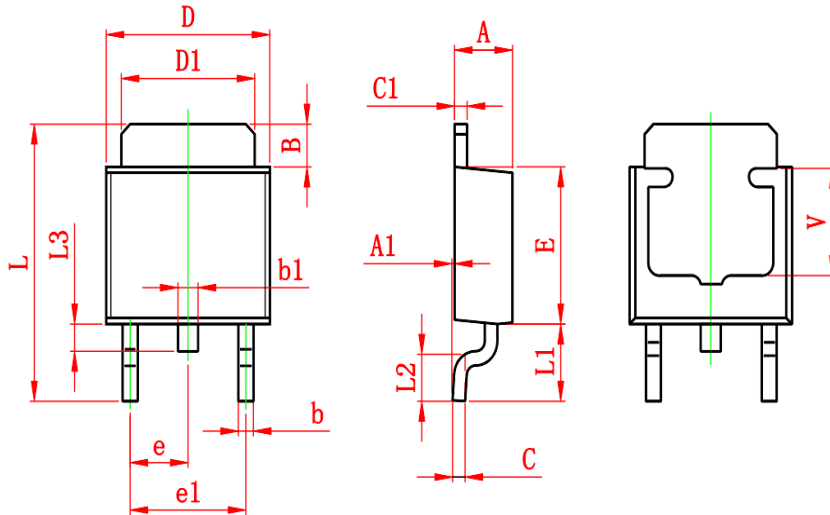


Figure 10. Switching wave

TO-252 Package Outline Drawing


Symbol	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
B	1.350	1.650	0.053	0.065
b	0.500	0.700	0.020	0.028
b1	0.700	0.900	0.028	0.035
c	0.430	0.580	0.017	0.023
c1	0.430	0.580	0.017	0.023
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.400	5.700	0.213	0.224
e	2.300 TYP.		0.091 TYP.	
e1	4.500	4.700	0.177	0.185
L	9.500	9.900	0.374	0.390
L1	2.550	2.900	0.100	0.114
L2	1.400	1.780	0.055	0.070
L3	0.600	0.900	0.024	0.035
V	3.800 REF.		0.150 REF.	